

SOT815-1

plastic, dual in-line compatible thermal enhanced very thin quad flat package; 24 terminals; 0.5 mm pitch; 3.5 mm x 5.5 mm x 0.85 mm body

26 February 2018

Package information

1. Package summary

| | |
|---------------------------------------|--|
| Terminal position code | Q (quad) |
| Package type descriptive code | DHVQFN24 |
| Package type industry code | DHVQFN24 |
| Package style descriptive code | DHVQFN (DIL-compatible thermal enhanced very thin quad flatpack; no leads) |
| Package body material type | P (plastic) |
| Mounting method type | S (surface mount) |
| Issue date | 29-4-2003 |
| Manufacturer package code | SOT815 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-----|-----|------|-----|------|
| D | package length | 5.4 | - | 5.5 | 5.6 | mm |
| E | package width | 3.4 | - | 3.5 | 3.6 | mm |
| A | seated height | - | - | 0.85 | 1 | mm |
| A ₂ | package height | - | - | 0.85 | - | mm |
| e | nominal pitch | - | - | 0.5 | - | mm |
| n ₂ | actual quantity of termination | - | - | 24 | - | A/A |

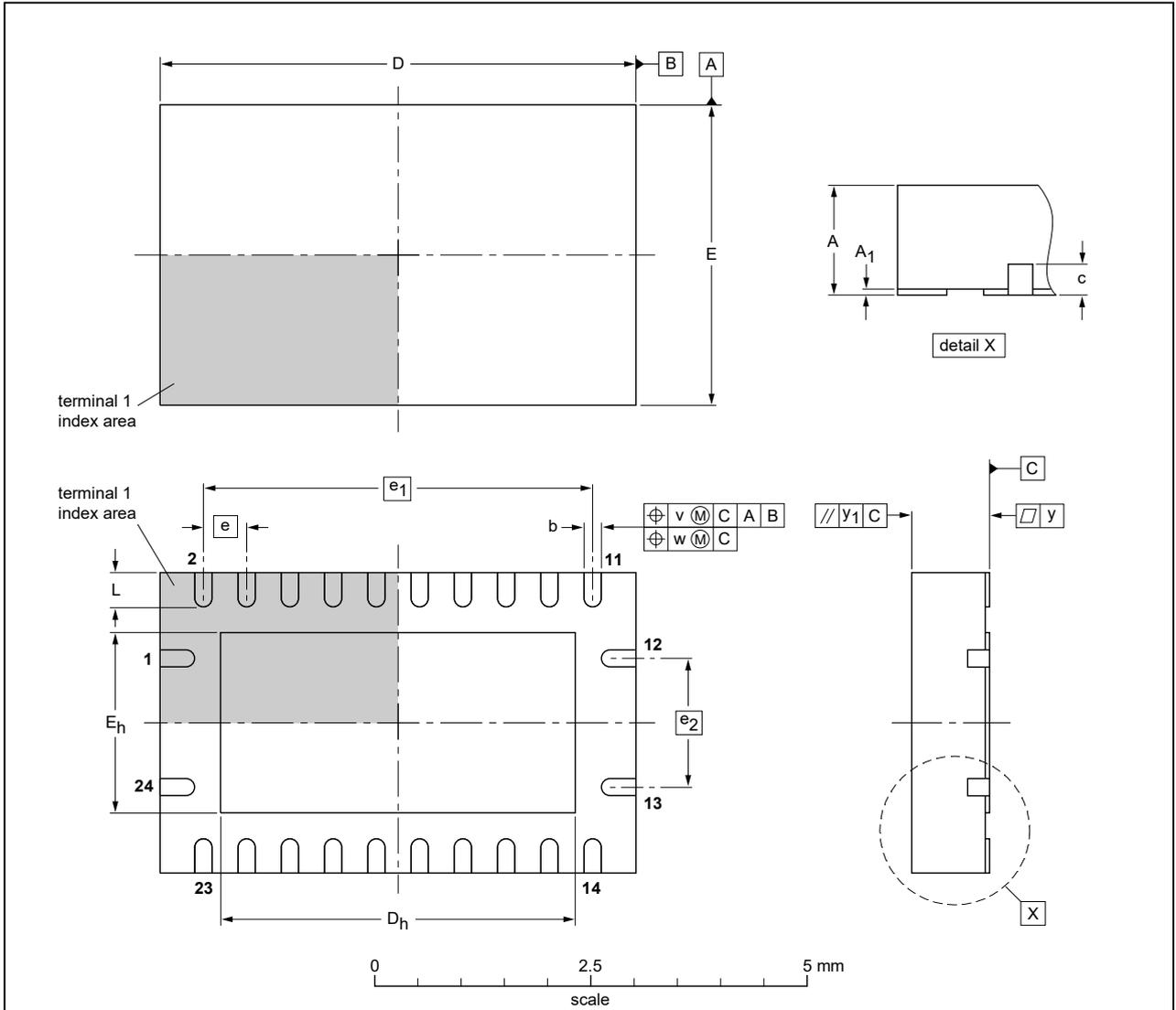


plastic, dual in-line compatible thermal enhanced very thin quad flat package; 24 terminals; 0.5 mm pitch; 3.5 mm x 5.5 mm x 0.85 mm body

2. Package outline

DHVQFN24: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 24 terminals; body 3.5 x 5.5 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

| UNIT | A ⁽¹⁾ max. | A ₁ | b | c | D ⁽¹⁾ | D _h | E ⁽¹⁾ | E _h | e | e ₁ | e ₂ | L | v | w | y | y ₁ |
|------|-----------------------|----------------|--------------|-----|------------------|----------------|------------------|----------------|-----|----------------|----------------|------------|-----|------|------|----------------|
| mm | 1 | 0.05 0.00 | 0.30 0.18 | 0.2 | 5.6 5.4 | 4.25 3.95 | 3.6 3.4 | 2.25 1.95 | 0.5 | 4.5 | 1.5 | 0.5 0.3 | 0.1 | 0.05 | 0.05 | 0.1 |

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|-------|-------|--|---------------------|------------|
| | IEC | JEDEC | JEITA | | | |
| SOT815-1 | --- | --- | --- | | | 03-04-29 |

Fig. 1. Package outline DHVQFN24 (SOT815-1)

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3. Soldering

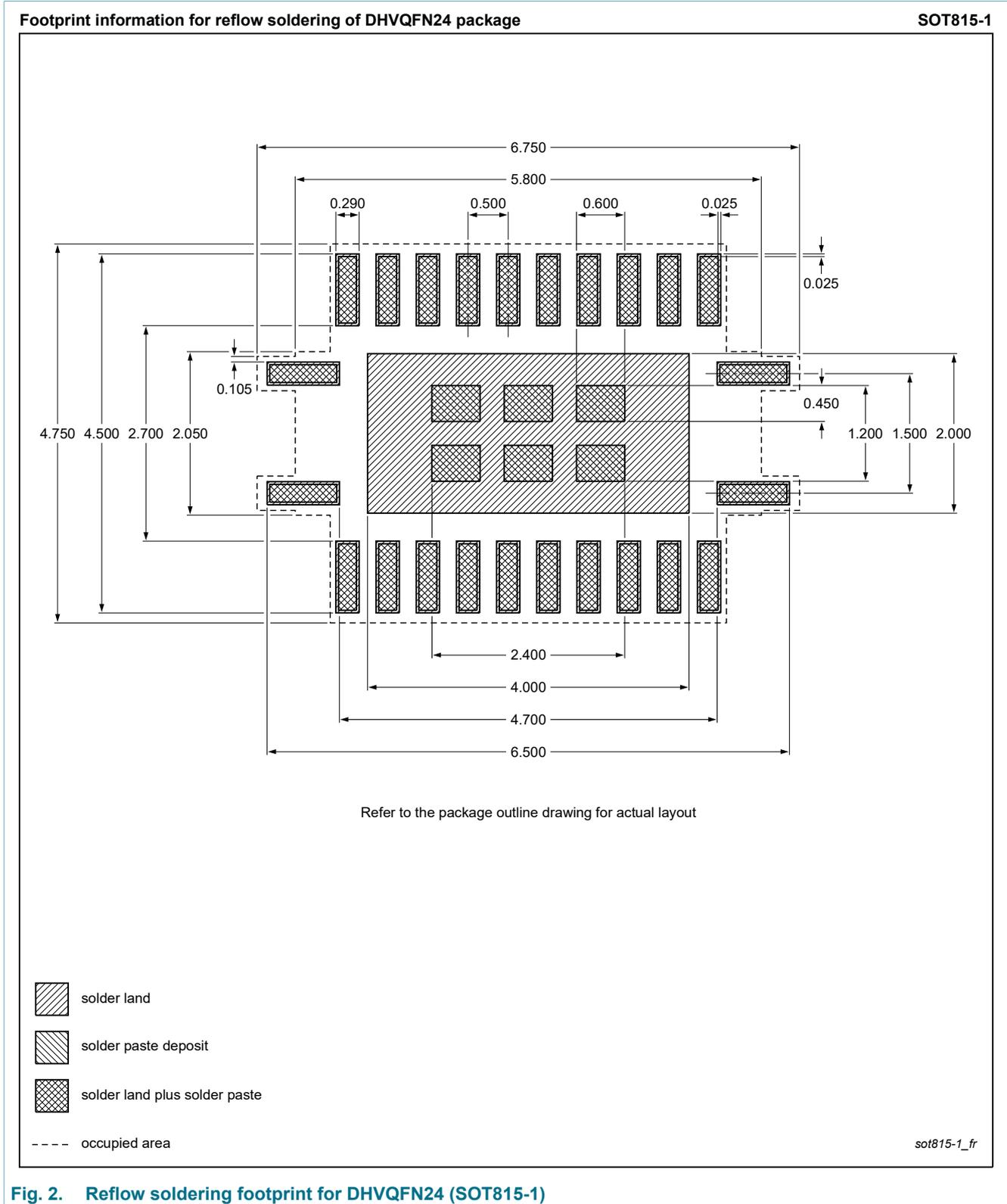


Fig. 2. Reflow soldering footprint for DHVQFN24 (SOT815-1)

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4. Legal information

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5. Contents

| | |
|---------------------------|---|
| 1. Package summary..... | 1 |
| 2. Package outline..... | 2 |
| 3. Soldering..... | 3 |
| 4. Legal information..... | 4 |

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For sales office addresses, please send an email to: salesaddresses@nxp.com

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